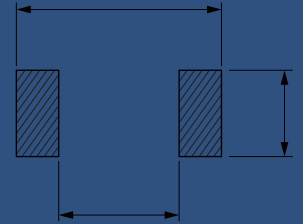
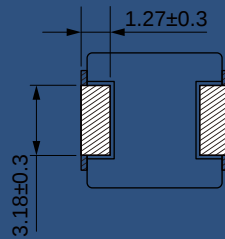


## FEATURES

- High performance realized by metal dust core and hot pressing process.
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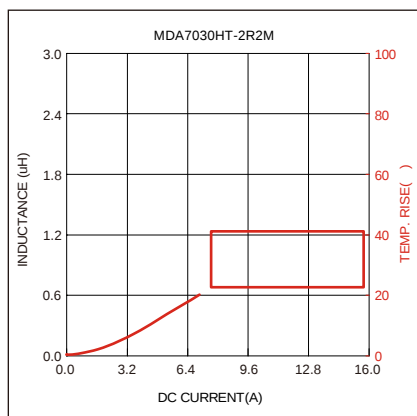
## APPLICATION

- Thermal management products, such as water pumps and valves
- 
- HVAC



| MDA7030HT-R47M | 0.47 | ±20% | 17.0 | 15.3 | 16.3 | 14.0 | 4.62 |
|----------------|------|------|------|------|------|------|------|
| MDA7030HT-R68M | 0.68 | ±20% | 16.5 | 14.1 | 13.0 | 11.0 | 5.30 |
| MDA7030HT-1R0M | 1.00 | ±20% | 13.0 | 11.7 | 13.0 | 11.1 | 7.80 |
| MDA7030HT-1R5M | 1.50 | ±20% | 10.6 | 9.5  | 11.6 | 9.9  | 12.5 |
| MDA7030HT-2R2M | 2.20 | ±20% | 9.0  | 8.1  | 8.0  | 6.9  | 16.5 |
| MDA7030HT-3R3M | 3.30 | ±20% | 7.5  | 6.8  | 8.3  | 7.1  | 26.0 |
| MDA7030HT-4R7M | 4.70 | ±20% | 6.0  | 5.4  | 6.0  | 5.1  | 33.4 |
| MDA7030HT-6R8M | 6.80 | ±20% | 5.5  | 5.0  | 4.5  | 3.9  | 46.8 |
| MDA7030HT-100M | 10.0 | ±20% | 4.0  | 3.6  | 3.5  | 3.0  | 70.5 |
| MDA7030HT-150M | 15.0 | ±20% | 3.2  | 2.9  | 2.8  | 2.4  | 110  |
| MDA7030HT-220M | 22.0 | ±20% | 2.8  | 2.5  | 2.4  | 2.1  | 174  |

## Typical Electrical Characteristics:

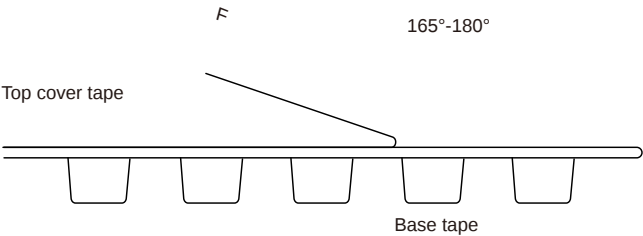


Soldering Reflow:

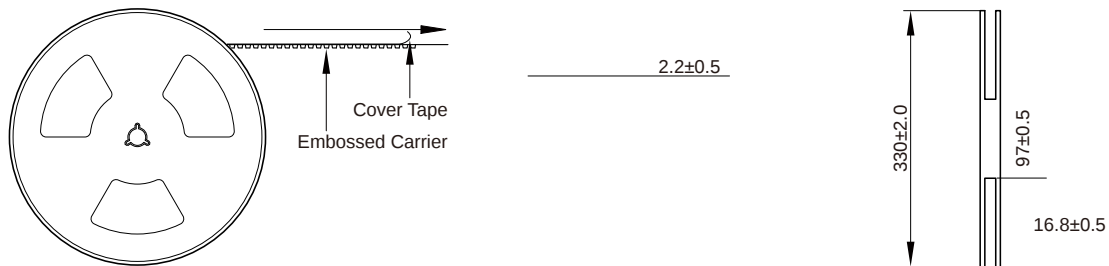
Packaging Information:

Tape Dimension :

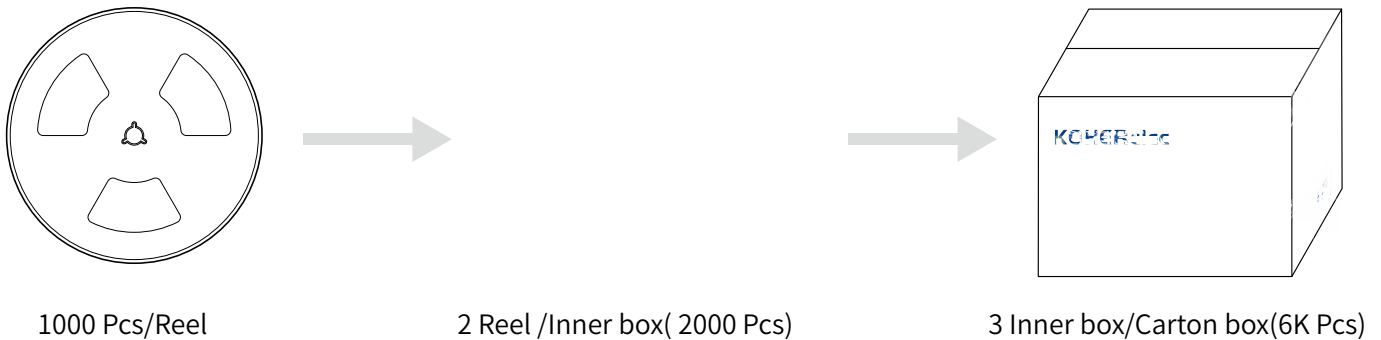
Peel force of top cover tape:



## Reel Dimension : [mm]



## Packaging Quantity:



## Cautions and Warnings:

### Storage Conditions :

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

### Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the